Please amend the present application as follows:

Claims

The following is a copy of Applicants' claims that identifies language being added with underlining ("___") and language being deleted with strikethrough ("—"), as is applicable:

1. (Currently Amended) A method for controlling fans comprising:

~~arranging~~ directly connecting a ~~combination~~ plurality of thermal sensors together in a parallel electrical configuration;

directly connecting ~~coupling~~ the ~~combination~~ plurality of thermal sensors to a thermal data channel of a controller; and

controlling cooling devices in accordance with the thermal data channel.

2. (Currently Amended) The method of claim 1, ~~wherein arranging~~ further comprising ~~comprises~~ placing the thermal sensors in proximity to electrical devices.

3. (Currently Amended) The method of claim 2, wherein placing the thermal sensors in proximity to the electrical devices comprises ~~are~~ placing the thermal sensors in proximity to processors.

4. (Canceled)

5. (Currently Amended) The method of claim 41, wherein directly connecting a plurality of thermal sensors in a parallel electrical configuration comprises connecting a plurality of ~~the~~ thermal sensors ~~are~~ constructed to respond uniformly to changes in temperature.

6. (Currently Amended) The method of claim 1, wherein directly connecting a plurality of thermal sensors in a parallel electrical configuration comprises connecting a plurality of ~~the thermal sensors are~~ diodes.

7. (Currently Amended) The method of claim 1, wherein directly connecting a plurality of thermal sensors in a parallel electrical configuration comprises connecting a plurality of ~~the thermal sensors are~~ transistors.

8. (Currently Amended) The method of claim 1, further comprising installing the controller and the ~~combination~~ plurality of thermal sensors in an electronic enclosure.

9. (Currently Amended) An electronic assembly comprising:

means for housing a plurality of active integrated circuit devices; and

means for controlling cooling devices proximal to select integrated circuit devices, wherein said means for controlling cooling devices is coupled to a combination of a first thermal sensing means directly connected in a parallel electrical configuration to ~~and~~ a second thermal sensing means, wherein said means for controlling cooling devices uses a single thermal data channel directly connected to the first and second thermal sensing means to sense thermal information provided by the first and second thermal sensing means.

10. (Canceled)

11. (Original) The electronic assembly of claim 9, wherein said means for controlling cooling devices drives a first cooling device located proximal to a first processor and a second cooling device located proximal to a second processor.

12. (Original) The electronic assembly of claim 11, wherein said means for controlling cooling devices drives the first and second fans in response to the warmest of the first processor and the second processor.

13. (Canceled)

14. (Currently Amended) An apparatus comprising:

a first device fan located proximal to a first select electrical device;

a second device fan located proximal to a second select electrical device;

a ~~combination of a~~ first thermal sensor directly connected in a parallel electrical configuration to ~~and~~ a second thermal sensor, wherein the first thermal sensor is located proximal to the first select electrical device and the second thermal sensor is located proximal to the second select electrical device; and

a fan controller having a first thermal data channel connected directly ~~coupled~~ to the ~~combination of the~~ first and second thermal sensors.

15. (Original) The apparatus of claim 14, wherein the fan controller senses the warmer of the first select electrical device and the second select electrical device and drives both the first device fan and the second device fan in accordance with a thermal operating profile for the first and second select electrical devices.

16. (Original) The apparatus of claim 15, wherein the first select electrical device and the second select electrical device comprise integrated circuits.

17. (Original) The apparatus of claim 14, wherein the first and second thermal sensors respond uniformly to changes in temperature.

18. (Original) The apparatus of claim 14, wherein the first and second thermal sensors are diodes.

19. (Original) The apparatus of claim 14, wherein the first and second thermal sensors are transistors.

20. (Original) The apparatus of claim 14, wherein the first device fan and the second device fan are substantially similar.

21. (Original) The apparatus of claim 14, further comprising:

an enclosure having an enclosure fan and a third thermal sensor coupled to a second thermal data channel of the fan controller.

22. (Original) The apparatus of claim 21, wherein the fan controller senses temperature using the third thermal sensor and the second thermal data channel and drives the enclosure fan in accordance with a thermal operating profile for the enclosure.